

01-28-2002



101962450

FORM PTO-1595

Docket Number: TI-33385

RECORDATION FORT COVER SHEET

Patents Only

U.S. Department of Commerce
Patent and Trademark Office

To the Ass't Commissioner for Patents. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Ray D. Harrison
Jianbai Zhu
Kendall S. Wills
Willmar Subido

01/11/02

2. Name and Address of receiving party(ies):

Name: Texas Instruments Incorporated
Address: P. O. Box 655474 M/S 3999
City: Dallas, TX 75265
Country: United States of America
Additional name(s) & address(es) attached? Yes ☒ No

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: January 11, 2002, January 11, 2002, January 10, 2002, and January 11, 2002

4. Application number(s) or patent number(s).

☒ This document is being filed together with a new application.

Execution date of the application: January 11, 2002

Title: Repackaging Semiconductor IC Devices for Failure Analysis

A. Patent Application No.(s)

S.N

Additional number attached? ☐ Yes ☒ No

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Mike Skrehot
Texas Instruments Incorporated
P. O. Box 655474, M/S 3999
Dallas, TX 75265
Tel: (972) 917-5633
TI-327696. Number of applications and patents involved: (1)

7. Amount of fee enclosed or authorized to be charged: \$40.

8. Deposit Account No: 20-0668

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date

1/11/02

Robert C. Klinge, 34,365

Total Number of Pages Including Cover Sheet, Attachments and Document: 201/25/2002 AAHME1 00000118 200668 10044024
01 FC:581 40.00 CH

3: 3068371v1

PATENT
REEL: 012498 FRAME: 0881

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

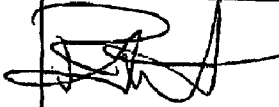
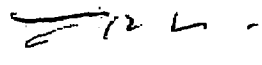
WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with its principal office at 7839 Churchill Way, M/S. 3999, Dallas, TX 75251, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefore, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute my said all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE OF INVENTION	REPACKAGING SEMICONDUCTOR IC DEVICES FOR FAILURE ANALYSIS		
SIGNATURE OF INVENTOR AND NAME	(1) Ray D. Harrison 	(2) Jianbai Zhu 	(3) Kendall S. Wills
DATE	01/11/02	01/11/02	
RESIDENCE (City, County, State)	Garland, Dallas, Texas	Plano, Collin, Texas	Sugarland, Fort Bend, Texas

Mike Skrehot
Texas Instruments Incorporated
P. O. Box 655474, M/S 3999
Dallas, TX 75265

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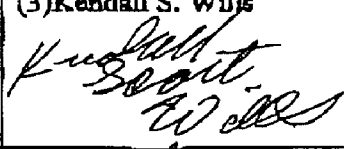
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SIGNATURE OF INVENTOR AND NAME	(1)Ray D. Harrison	(2) Jimbai Zhu	(3)Kendall S. Wills 
DATE			1/10/2002
RESIDENCE (City, County, State)	Garland, Dallas, Texas	Plano, Collin, Texas	Sugarland, Fort Bend, Texas

Mike Skrehot
Texas Instruments Incorporated
P. O. Box 655474, M/S 3999
Dallas, TX 75265

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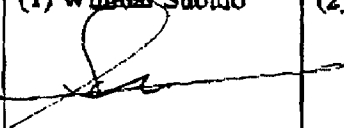
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TITLE OF INVENTION	REPACKAGING SEMICONDUCTOR IC DEVICES FOR FAILURE ANALYSIS		
SIGNATURE OF INVENTOR AND NAME	(1) Wilmar Subido 	(2)	(3)
DATE	01/11/02		
RESIDENCE (City, County, State)	Garland, Dallas, Texas		

Mike Skrehor
Texas Instruments Incorporated
P. O. Box 655474, M/S 3999
Dallas, TX 75265

7: 3068371v1

RECORDED: 01/11/2002

PATENT
REEL: 012498 FRAME: 0884